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# ***Optoelectronic Interconnects XII***

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**Ray T. Chen**  
*Editors*

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# Contents

- vii *Conference Committee*
- ix *Spinoptics: Spin degeneracy removal in nanostructures (Plenary Paper) [8269-100]*  
*V. Kleiner, N. Shitrit, E. Hasman, Technion-Israel Institute of Technology (Israel)*

---

## SESSION 1 OPTICAL PCB I

---

- 8267 03 **Injection molded optical backplane for broadcast architecture (Invited Paper) [8267-02]**  
P. Rosenberg, S. Mathai, W. V. Sorin, Hewlett-Packard Co. (United States); M. McLaren, Hewlett-Packard Ltd. (United Kingdom); J. Straznicky, G. Panotopoulos, D. Warren, T. Morris, M. R. T. Tan, Hewlett-Packard Co. (United States)
- 8267 04 **Evaluation of multimode optical waveguides for optical bus interconnects [8267-49]**  
A. X. Wang, Oregon State Univ. (United States)
- 8267 06 **Design of a highly parallel board-level-interconnection with 320 Gbps capacity [8267-04]**  
U. Lohmann, J. Jahns, FernUniv. in Hagen (Germany); S. Limmer, D. Fey, Friedrich-Alexander-Univ. Erlangen-Nürnberg (Germany); H. Bauer, MICROSENS GmbH & Co. KG (Germany)

---

## SESSION 2 OPTICAL PCB II

---

- 8267 09 **Polymer optical waveguide-based bi-directional optical bus architecture for high-speed optical backplane [8267-07]**  
X. Lin, X. Dou, The Univ. of Texas at Austin (United States); A. X. Wang, Oregon State Univ. (United States); R. T. Chen, The Univ. of Texas at Austin (United States)
- 8267 0A **Characterization and analysis of graded index optical waveguides for the realization of low-power, high-density, and high-speed optical link [8267-08]**  
H.-H. Hsu, Keio Univ. (Japan) and IBM Research - Tokyo (Japan); T. Ishigure, Keio Univ. (Japan); S. Nakagawa, IBM Research - Tokyo (Japan)

---

## SESSION 3 INTEGRATED TX/RX MODULES

---

- 8267 0B **Heterogeneous photonic integrated circuits (Invited Paper) [8267-09]**  
A. W. Fang, G. Fish, E. Hall, Aurrion, Inc. (United States)
- 8267 0C **A 25-Gbps high-sensitivity optical receiver with 10-Gbps photodiode using inductive input coupling for optical interconnects [8267-10]**  
H. Oku, K. Narita, T. Shiraishi, S. Ide, K. Tanaka, Fujitsu Labs., Ltd. (Japan)

- 8267 OD **4 channels x 10-Gbps optoelectronic transceiver based on silicon optical bench technology** [8267-11]  
C. T. Chen, H. L. Hsiao, C. C. Chang, P. K. Shen, G. F. Lu, National Central Univ. (Taiwan); Y. C. Lee, Centera Photonics Inc. (Taiwan); S. F. Chang, Y. S. Lin, M. L. Wu, National Central Univ. (Taiwan)
- 8267 OE **Multigigabit optical transceivers for high-data rate military applications** [8267-12]  
B. E. Catanzaro, CFE Services (United States); C. Kuznia, Ultra Communications, Inc. (United States)

---

#### SESSION 4 SI PHOTONICS FOR INTERCONNECTS

---

- 8267 OF **Si-based optical I/O for optical memory interface (Invited Paper)** [8267-13]  
K. Ha, D. Shin, H. Byun, K. Cho, K. Na, H. Ji, J. Pyo, S. Hong, K. Lee, B. Lee, Y. Shin, J. Kim, S. Kim, I. Joe, S. Suh, S. Choi, S. Han, Y. Park, H. Choi, B. Kuh, K. Kim, J. Choi, S. Park, H. Kim, K. Kim, J. Choi, H. Lee, S. Yang, S. Park, M. Lee, M. Cho, S. Kim, T. Jeong, S. Hyun, C. Cho, J. Kim, H. Yoon, J. Nam, H. Kwon, H. Lee, J. Choi, S. Jang, J. Choi, C. Chung, SAMSUNG Electronics Co., Ltd. (Korea, Republic of)
- 8267 OH **Silicon nanomembranes for high-performance flexible photonic interconnects and devices** [8267-15]  
H. Subbaraman, Omega Optics, Inc. (United States); X. Xu, N. Rahimi, The Univ. of Texas at Austin (United States); A. Hosseini, Omega Optics, Inc. (United States); R. T. Chen, The Univ. of Texas at Austin (United States)
- 8267 OI **Low insertion loss modulator based on a vertically coupled photonic crystal resonator** [8267-16]  
K. Debnath, L. O'Faolain, Univ. of St. Andrews (United Kingdom); F. Y. Gardes, D. Thomson, G. Reed, Univ. of Surrey (United Kingdom); T. F. Krauss, Univ. of St. Andrews (United Kingdom)

---

#### SESSION 5 WAVEGUIDES FOR OPTO-PCB

---

- 8267 OJ **Link power budget advantage in GI-core polymer optical waveguide link for optical printed circuit boards** [8267-17]  
S. Yakabe, Keio Univ. (Japan) and IBM Research - Tokyo (Japan); T. Ishigure, Keio Univ. (Japan); S. Nakagawa, IBM Research - Tokyo (Japan)
- 8267 OK **Novel optical interconnect devices applying mask-transfer self-written method** [8267-18]  
N. Ishizawa, Y. Matsuzawa, Y. Tokiwa, K. Nakama, O. Mikami, Tokai Univ. (Japan)
- 8267 OM **Single-mode glass waveguide technology for optical interchip communication on board level** [8267-20]  
L. Brusberg, M. Neitz, H. Schröder, Fraunhofer-Institut für Zuverlässigkeit und Mikrointegration (Germany)
- 8267 ON **Optical waveguide end roughness in correlation to optical coupling** [8267-21]  
K. Kruse, N. Riegel, Michigan Technological Univ. (United States); C. Demars, Calumet Electronics Corp. (United States); C. Middlebrook, M. Roggemann, Michigan Technological Univ. (United States)

---

**SESSION 6 PASSIVE COMPONENTS**

---

- 8267 0O **Next-generation, high-density, low-cost, multimode optical backplane interconnect (Invited Paper)** [8267-22]  
D. Childers, E. Childers, J. Graham, M. Hughes, US Conec Ltd. (United States)
- 8267 0P **Rapid prototyping of interfacing microcomponents for printed circuit board-level optical interconnects (Invited Paper)** [8267-23]  
J. Van Erps, M. Vervaeke, H. Thienpont, Vrije Univ. Brussel (Belgium)
- 8267 0R **Soft lithography fabricated polymer waveguides and 45° inclined mirrors for card-to-backplane optical interconnects** [8267-25]  
G. Jiang, S. Baig, M. R. Wang, Univ. of Miami (United States)

---

**SESSION 7 PACKAGING AND INTEGRATION**

---

- 8267 0S **Aspects of short-range interconnect packaging (Invited Paper)** [8267-26]  
D. Wohlfeld, K.-H. Brenner, Ruprecht-Karls-Univ. Heidelberg (Germany)
- 8267 0T **Novel coupling and packaging approaches for optical interconnects (Invited Paper)** [8267-27]  
B. Van Hoe, E. Bosman, J. Missinne, S. Kalathimekkad, G. Van Steenberge, P. Van Daele, Univ. Gent (Belgium)
- 8267 0U **Chip-to-chip interconnects based on 3D stacking of optoelectrical dies on Si** [8267-28]  
P. Duan, O. Raz, B. E. Smalbrugge, Technische Univ. Eindhoven (Netherlands); J. Duis, TE Connectivity Ltd. (Netherlands); H. J. S. Dorren, Technische Univ. Eindhoven (Netherlands)
- 8267 0V **Proposal and FDTD simulation of reflective self-organizing lightwave network (R-SOLNET) using phosphor** [8267-29]  
M. Seki, T. Yoshimura, Tokyo Univ. of Technology (Japan)

---

**SESSION 8 OPTICAL INTERCONNECTS IN HIGH PERFORMANCE COMPUTING: JOINT SESSION WITH CONFERENCE 8265**

---

- 8267 0W **Optics in computers, servers, and data centers (Invited Paper)** [8267-30]  
H. J. S. Dorren, P. Duan, O. Raz, Technische Univ. Eindhoven (Netherlands); R. P. Lujtjen, IBM Research GmbH (Switzerland)
- 8267 0X **Chip-scale integrated optical interconnects: a key enabler for future high-performance computing (Invited Paper)** [8267-31]  
M. Haney, R. Nair, T. Gu, Univ. of Delaware (United States)

---

**SESSION 9 NANOPHOTONICS FOR OPTICAL INTERCONNECTS: JOINT SESSION WITH CONFERENCE 8265**

---

- 8267 0Z **Low-power integration of on-chip nanophotonic interconnect for high-performance optoelectrical IC (Invited Paper)** [8267-33]  
D. Ding, D. Z. Pan, The Univ. of Texas at Austin (United States)

---

**SESSION 10 COMPONENTS**

---

- 8267 12 **Design and experimental study on the grating outcouplers providing the controlled 2D-intensity profile of the output beam from a broad area laser diode** [8267-36]  
O. V. Smolski, V. O. Smolski, E. C. Browy, E. G. Johnson, The Univ. of North Carolina at Charlotte (United States); Z. A. Shellenbarger, SRI International Sarnoff (United States)
- 8267 13 **Novel VCSEL driving technique with virtual back termination for high-speed optical interconnection** [8267-37]  
M. Sugawara, Y. Tsunoda, H. Oku, S. Ide, K. Tanaka, Fujitsu Labs., Ltd. (Japan)

---

**SESSION 11 OPTICAL LINKS**

---

- 8267 14 **Application of MIMO technology for next-generation optical and millimeter-wave interconnects (Invited Paper)** [8267-38]  
S.-H. Fan, Georgia Institute of Technology (United States); D. Guidotti, Institute of Microelectronics (China); G.-K. Chang, Georgia Institute of Technology (United States)
- 8267 15 **Device design and signal processing for multiple-input multiple-output multimode fiber links (Invited Paper)** [8267-39]  
K. Appaiah, S. Vishwanath, S. R. Bank, The Univ. of Texas at Austin (United States)
- 8267 16 **A high-speed 0.35 $\mu$ m CMOS optical communication link** [8267-40]  
M. E. Goosen, INSiAVA (Pty) Ltd. (South Africa); P. J. Venter, M. du Plessis, Univ. of Pretoria (South Africa); A. W. Bogalecki, A. C. Alberts, P. Rademeyer, INSiAVA (Pty) Ltd. (South Africa)

---

**POSTER SESSION**

---

- 8267 19 **Design and fabrication of a 1-by-4 multimode interference splitter** [8267-42]  
M. Li Institute of Semiconductors (China) and Tsinghua Univ. (China); H. Zhu, Institute of Semiconductors (China); M. Chen, Tsinghua Univ. (China)
- 8267 1A **Transmitting part of optical interconnect module with three-dimensional optical path** [8267-43]  
C.-C. Chang, P.-K. Shen, C.-T. Chen, H.-L. Hsiao, Y.-C. Chang, National Central Univ. (Taiwan); Y.-C. Lee, Centera Photonics Inc. (Taiwan); M.-L. Wu, National Central Univ. (Taiwan)
- 8267 1B **Improved performance of traveling wave directional coupler modulator based on electro-optic polymer** [8267-44]  
X. Zhang, B. Lee, C. Lin, The Univ. of Texas at Austin (United States); A. X. Wang, Oregon State Univ. (United States); A. Hosseini, Omega Optics, Inc. (United States); X. Lin, R. T. Chen, The Univ. of Texas at Austin (United States)
- 8267 1C **80 $\mu$ m-core graded-index MMF for consumer electronic devices** [8267-46]  
D. Molin, M. Bigot-Astruc, P. Sillard, Prysmian Group (France)

*Author Index*

# Conference Committee

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    **Tetsuzo Yoshimura**, Tokyo University of Technology (Japan)
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    **Hyo-Hoon Park**, KAIST (Korea, Republic of)
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- 6    Passive Components  
    **Michael R. Wang**, University of Miami (United States)
- 7    Packaging and Integration  
    **Ulrich Lohmann**, FernUniversität in Hagen (Germany)
- 8    Optical Interconnects in High Performance Computing: Joint Session  
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    **Louay A. Eldada**, SunEdison (United States)
- 9    Nanophotonics for Optical Interconnects: Joint Session with  
    Conference 8265  
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